

BO-JIANG

帛江科技股份有限公司

BO-JIANG TECHNOLOGY CO., LTD.

PRODUCT SPECIFICATION (產品規格書)

PART NO.(圖號)	7065NR702BF002B	DATE (日期)	2009 / 09 / 22
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TITLE(產品名稱)	BNC R/A PCB MOUNT JACK (75 ohms)		
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MATERIAL AND FINISH(材質及表面處理)

DESCRIPTION(名稱)	MATERIAL(材質)	FINISH(表面處理)
Center Contact(中心導體)	BRASS	GOLD FLUSH
Insulator(絕緣體)	TEFLON	WHITE
Outer Contact(外導體)	BRASS	70u" NICKEL
Others(其它)	BRACKET	100u" TIN

ELECTRICAL(電氣特性)

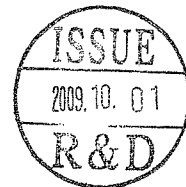
項目	測試條件	測試規格	
Impedance(阻抗)	0 ~ 1 GHz	75 Ω	
Voltage Standing Wave Ratio(VSWR)(駐波比)	0 ~ 800 MHz	1.3 Max.	
Dielectric Withstanding Voltage(絕緣耐電壓)	DC, time: 60sec	1500 Vrms Min.	
Contact Resistance (導體阻抗)	Center Contact (中心導體)	DC 0.2V, 1A	3 mΩ Max.
	Outer Contact(外導體)	DC 0.2V, 1A	2 mΩ Max.
Insulation Resistance(絕緣阻抗)	DC 500V, time: 60sec	5000 MΩ Min.	

MECHANICAL(機械特性)

項目	測試條件	測試規格
Force To Engage/Disengage(接合力/脫離力):	N/A	2.5 in-lbs max. / 3 lbs max.
Contact Retention(中心導體承受力):	60mm/min	6 lbs min.

REMARKS(備註)

- Between BODY (NO.1) And LOCK RING (NO.3) Must Withstand A 18 lbs. Min. Axial Force. (軸向力測試)。
- Between BODY (NO.1) And BRACKET (NO.5) Must Withstand A 20 lbs. Min. Axial Force And A 5 in-lbs. Min. Torque Force. (軸向力和扭力測試)。



A	N/A	<i>[Signature]</i>	<i>[Signature]</i>	<i>[Signature]</i>
Issue 版本	Revision 修改記錄	Approved 核准	Checked 審核	Drawn 製定